

(19)



JAPANESE PATENT OFFICE

PATENT ABSTRACTS OF JAPAN

(11) Publication number: **11307927 A**(43) Date of publication of application: **05.11.99**

(51) Int. Cl.

H05K 3/34(21) Application number: **10115170**(71) Applicant: **SONY CORP**(22) Date of filing: **24.04.98**(72) Inventor: **TSURUSAKI ARATA**(54) **SOLDERING EQUIPMENT AND SOLDERING METHOD**

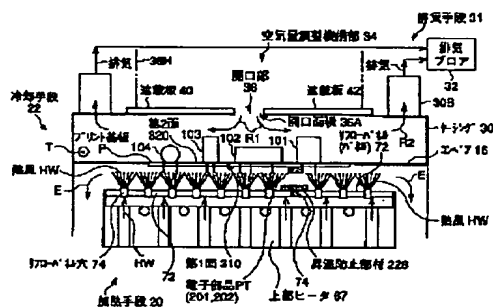
surface 310 side, out of the holes 74 in the hot air supplying panel 72.

(57) Abstract:

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PROBLEM TO BE SOLVED: To effectively heat a soldering part of a board while cooling effectively a component which is not heat resistant and mounted on the board, and prevent temperature rise of the component to be exposed at the time of heating.

SOLUTION: This soldering equipment heats a soldering part of a component which is not heat resistant, in order to electrically connect the component with a board, and is provided with a heating means 20 which supplies hot air to a first surface side 310 of a soldering part side of the component of the board and heats the soldering part, and a cooling means 22 for cooling a second surface 320 side of the board on whose surface the component is mounted. The heating means 20 is provided with a heat air supplying panel 72 having many holes 74 for supplying hot air wholly to the first surface 310 side, and a temperature rise preventing member 228 for preventing temperature rise of components arranged on the first surface 310 side by selectively closing the holes 74 at positions corresponding to the components arranged on the first

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